

Automotive Grade AUIRS2184(4)S

HALF-BRIDGE DRIVER

Features

- Floating channel designed for bootstrap operation
- Fully operational to + 600 V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 V to 20 V
- Undervoltage lockout for both channels
- 3.3 V and 5 V input logic compatible
- Matched propagation delay for both channels
- Logic and power ground +/- 5 V offset
- Lower di/dt gate driver for better noise immunity
- Output source/sink current capability (typical) 1.9 A/2.3 A
- Lead free, RoHS compliant
- Automotive Qualified*

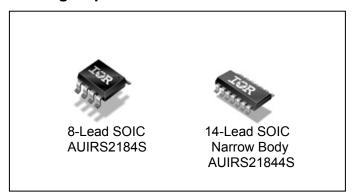
Typical Applications

- DC/DC converter
- pump and compressor
- piezo injection
- Starter/ alternator

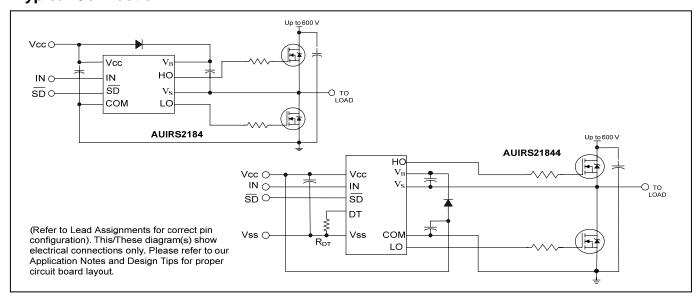
Product Summary

Topology	Half-Bridge
V _{OFFSET}	600 V
V _{OUT}	10 V – 20 V
I _{o+} & I _{o-} (typical)	1.9 A & 2.3 A
t _{on} & t _{off} (typical)	600 ns & 230 ns
Deadtime (typical)	400 ns (R _{DT} = 0 Ω) 5 μs (R _{DT} = 200 kΩ)

Package Options



Typical Connection



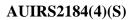




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Description

The AUIRS2184(4)S are high voltage, high speed power MOSFET and IGBT drivers with dependent high and low-side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3 V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high-side configuration which operates up to 600 V.

Feature Comparison: AUIRS2181(4)/AUIRS2183(4)/AUIRS2184(4)

Part	Input Logic	Cross- Conduction Prevention logic	Dead-Time	Ground Pins	Ton/Toff
2181				COM	160/200 ns
21814	HIN/LIN	no	none	V _{SS} /COM	100/200 115
2183			Internal 500ns	COM	160/200 ns
21834	HIN/LIN	yes	Programmable 0.4 – 5 us	V _{SS} /COM	100/200 115
2184			Internal 500ns	COM	600/220 pa
21844	IN/SD	yes	Programmable 0.4 – 5 us	V _{SS} /COM	600/230 ns



Qualification Information[†]

Qualification info	manon						
		Automotive (per AEC-Q100 ^{††})					
Qualification Level		Comments: This family of ICs has passed an Automotive qualification. IR's Industrial and Consume qualification level is granted by extension of the highe Automotive level.					
Moisture Sensitivity Level		SOIC8	MSL3 ^{†††} 260°C				
		SOIC14N	(per IPC/JEDEC J-STD-020)				
	Machine Model	Class M1 (Pass +/-100V)					
	macinite inicae.	(per AEC-Q100-003)					
ESD	Human Body Model	Class H1C (Pass +/-1500V)					
202	Traman Body Woder	(per AEC-Q100-002)					
	Charged Davise Medal	Class C4 (Pass +/-1000V)					
Charged Device Model		(per AEC-Q100-011)					
IO Latabilla Taat		Class II, Level A ^{††††}					
IC Latch-Up Test (per AEC-Q100-004)			AEC-Q100-004)				
RoHS Compliant		Yes					

[†] Qualification standards can be found at International Rectifier's web site http://www.irf.com/

^{††} Exceptions to AEC-Q100 requirements are noted in the qualification report.

^{†††} Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

^{††††} IN, SD, DT Class II Level B at 40mA per JESD78.



Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM lead. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the "Recommended Operating Conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

Symbol	Definition		Min	Max	Units
V_B	High-side floating absolute voltage	-0.3	620		
Vs	High-side floating supply offset voltage		V _B - 25	V _B + 0.3	
V_{HO}	High-side floating output voltage		V_S - 0.3	V _B + 0.3	
V_{CC}	Low-side and logic fixed supply voltage		-0.3	20 [†]	V
V_{LO}	Low-side output voltage		-0.3	V _{CC} + 0.3	V
DT	Programmable deadtime pin voltage		$V_{\rm SS}$ -0.3	V _{CC} + 0.3	
V_{IN}	Logic input voltage (IN & SD)			V _{CC} + 0.3	
V_{SS}	Logic ground	V _{CC} - 20	$V_{CC} + 0.3$		
dV _S /dt	Allowable offset supply voltage transient			50	V/ns
D	Declare rever dissination @ TA < 25°C	(8-lead SOIC)	_	0.625	14/
P _D	Package power dissipation @ TA ≤ 25°C	(14-lead SOIC)	_	1.0	W
D.I.	-	(8-lead SOIC)	_	200	0000
Rth _{JA}	Thermal resistance, junction to ambient (14-lead SOIC)		_	120	°C/W
TJ	Junction temperature			150	
Ts	Storage temperature			150	°C
T _L	Lead temperature (soldering, 10 seconds)		_	300	

[†] All supplies are fully tested at 25 V and an internal 20 V clamp exists for each supply.



Recommended Operating Conditions

The input/output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. The $V_{\rm S}$ and $V_{\rm SS}$ offset rating are tested with all supplies biased at a 15 V differential.

Symbol	Definition	Min	Max	Units
V_{B}	High-side floating supply absolute voltage	V _S + 10	V _S + 20	
Vs	High-side floating supply offset voltage	(††)	600	
V_{HO}	High-side floating output voltage	Vs	V_B	
V_{CC}	Low-side and logic fixed supply voltage	10	20	V
V_{LO}	Low-side output voltage	0	V _{CC}	V
V_{IN}	Logic input voltage (IN & SD) (†††)	V_{SS}	V _{CC}	
DT	Programmable deadtime pin voltage	V_{SS}	V _{CC}	
V_{SS}	Logic ground	-5	5	
T _A	Ambient temperature	-40	125	လူ

^{††} Logic operational for V_S of -5 V to +600 V. Logic state held for V_S of -5 V to $-V_{BS}$. (Please refer to Design Tip DT97-3 for more details).

Dynamic Electrical Characteristics

Unless otherwise noted, these specifications apply for an operating junction temperature range of -40°C \leq Tj \leq 125°C with bias conditions of V_{BIAS} (V_{CC}, V_{BS}) = 15 V, V_{SS} = COM, C_L = 1000 pF.

Symbol	Definition	Min	Тур	Max	Units	Test Conditions
t _{on}	Turn-on propagation delay		600	900		$V_S = 0 V$
t_{off}	Turn-off propagation delay	_	230	400		$V_{S} = 0 \text{ V or } 600 \text{ V}$
t_{sd}	Shut-down propagation delay	_	220	350		
MT_{on}	Delay matching, HS & LS turn-on	_	3	90	ns	
MT_{off}	Delay matching , HS & LS turn-off	_	15	40	115	
t _r	Turn-on rise time	_	15	60		V _S = 0 V
t _f	Turn-off fall time	_	12	35		v _s – u v
DT	Deadtime: LO turn-off to HO turn-on (DT _{LO-HO}) &	280	375	520		$R_{DT} = 0 \Omega$
וט	HO turn-off to LO turn-on (DT _{HO-LO})	3.9	5	6	μs	R_{DT} = 200 k Ω
MDT	Deadtime matching DT DT	_	0	50	ns	$R_{DT} = 0 \Omega$
IVIDT	Deadtime matching DT _{LO-HO} - DT _{HO-LO}	_	0	600	115	R_{DT} = 200 k Ω

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^{†††} HIN and LIN are internally clamped with a 5.2 V zener diode.



Static Electrical Characteristics

Unless otherwise noted, these specifications apply for an operating junction temperature range of -40°C \leq Tj \leq 125°C with bias conditions of V_{BIAS} ($V_{CC},\ V_{BS}$) = 15 V, V_{SS} = COM. The $V_{IL,}\ V_{IH}$ and I_{IN} parameters are referenced to V_{SS} /COM and are applicable to the respective input leads: IN and \overline{SD} . The $V_{O,}\ I_{O}$ and R_{on} parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

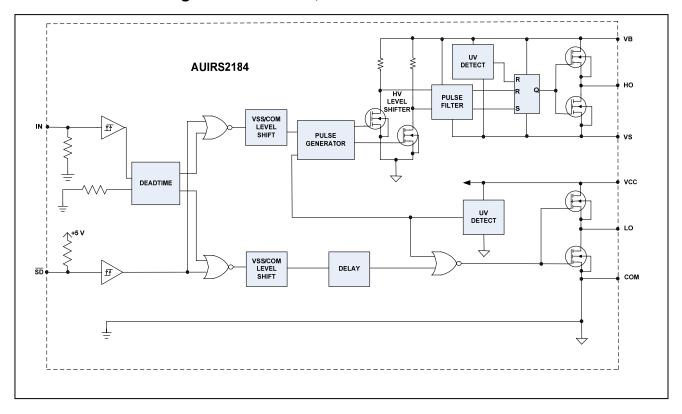
Symbol	Definition	Min	Тур	Max	Units	Test Conditions
V_{IH}	Logic "1" input voltage for HO & logic "0" for LO	2.5	_	_		
V_{IL}	Logic "0" input voltage for HO & logic "1" for LO	_	_	8.0		V _{CC} = 10 V to 20 V
$V_{SD,TH+}$	SD input positive going threshold	2.5	_	_	V	V _{CC} = 10 V to 20 V
$V_{SD,TH-}$	SD input negative going threshold	_	_	0.8	'	
V_{OH}	High level output voltage, V_{BIAS} - V_{O}	_	_	1.5		I _O = 0 A
V_{OL}	Low level output voltage, Vo	_	_	0.2		$I_O = 20 \text{ mA}$
I_{LK}	Offset supply leakage current	_	_	50	μA	$V_{B} = V_{S} = 600 \text{ V}$
I_{QBS}	Quiescent V _{BS} supply current	10	50	130	μΛ	V _{IN} = 0 V or 5 V
I _{QCC}	Quiescent V _{CC} supply current	0.4	1.0	1.3	mA	V _{IN} = 0 V OI 5 V
I _{IN+}	Logic "1" input bias current	_	25	60	μA	$IN = 5 \text{ V}, \overline{SD} = 0 \text{ V}$
I _{IN-}	Logic "0" input bias current	_	_	5.0	μΑ	IN = 0 V, SD = 5 V
$V_{\text{CCUV+}} \ V_{\text{BSUV+}}$	V_{CC} and V_{BS} supply undervoltage positive going threshold	8.0	8.9	9.8		
V _{CCUV-} V _{BSUV-}	V_{CC} and V_{BS} supply undervoltage negative going threshold	7.4	8.2	9.0	V	
$V_{\sf CCUVH} \ V_{\sf BSUVH}$	Hysteresis	0.3	0.7			
I _{O25+} ^(†)	Output high short circuit pulsed current	1.4	1.9	_		$V_O = 0V$, $PW \le 10us$, $T_J = 25$ °C
I _{O25-} ^(†)	Output low short circuit pulsed current	1.8	2.3	_	Α	V_O = 15V, PW \leq 10us, T_J = 25°C
$I_{O^+}^{(\dagger)(\dagger\dagger)}$	Output high short circuit pulsed current	1.2	_	_		$V_O = 0 V$, PW $\leq 10 \mu s$
I _{O-} ^(†) (††)	Output low short circuit pulsed current	1.5	_	_		V _O = 15 V, PW ≤ 10 μs

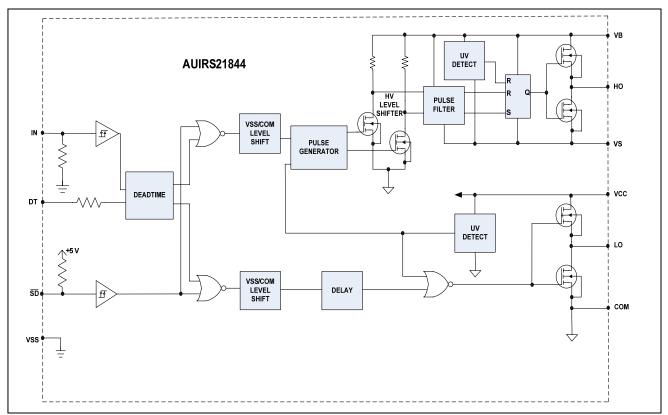
^(†) Guaranteed by design

^(††) I_{O+} and I_{O-} decrease with rising temperature

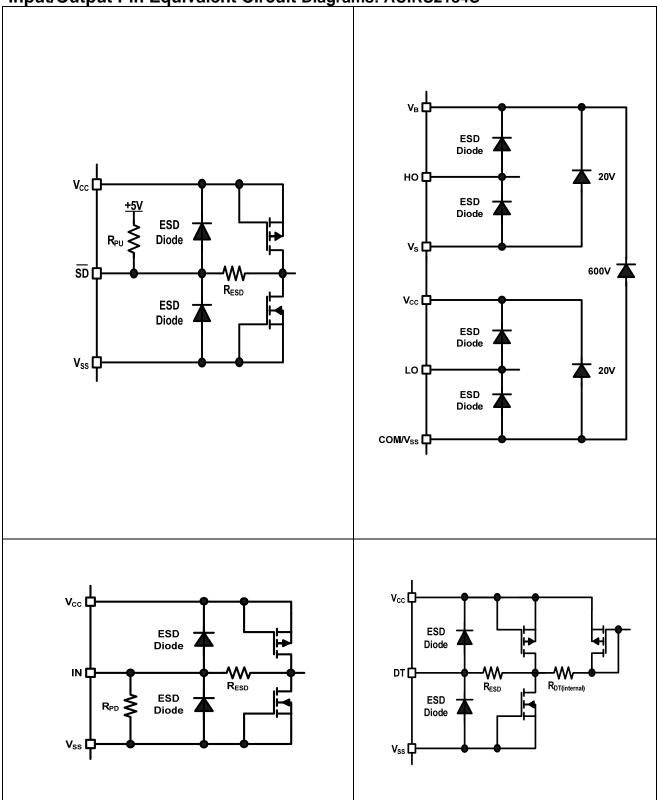


Functional Block Diagram: AUIRS2184, AUIRS21844

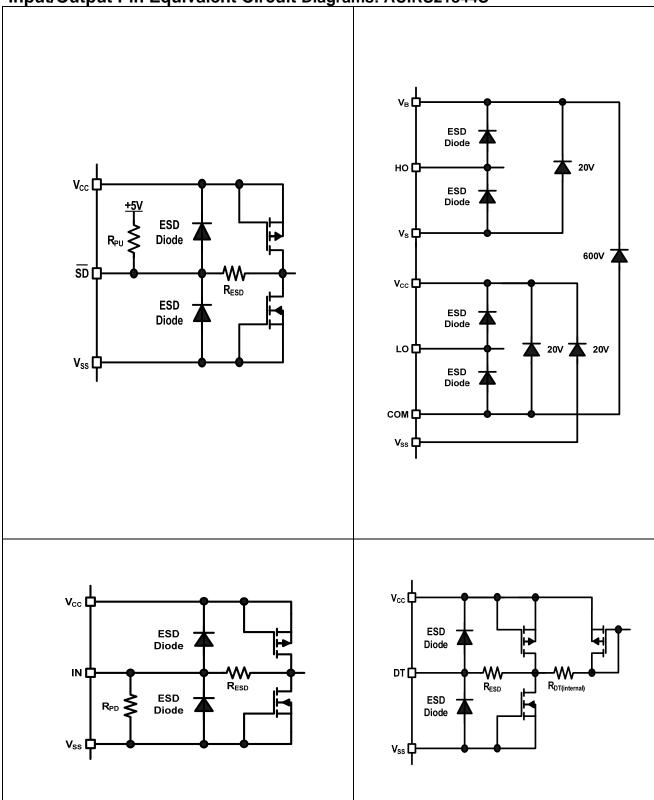




Input/Output Pin Equivalent Circuit Diagrams: AUIRS2184S



Input/Output Pin Equivalent Circuit Diagrams: AUIRS21844S

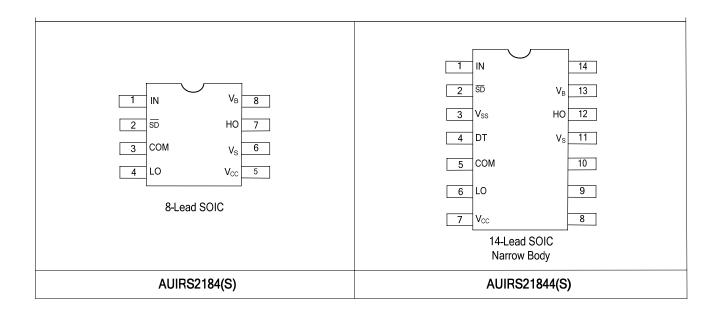




Lead Definitions

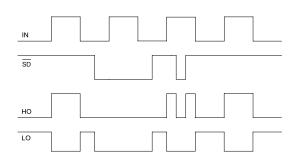
Symbol	Description
IN	Logic input for high-side and low-side gate driver outputs (HO and LO), in phase with HO (referenced to COM for AUIRS2184 and $V_{\rm SS}$ for AUIRS21844)
SD	Logic input for shutdown (referenced to COM for AUIRS2184 and V _{SS} for AUIRS21844)
DT	Programmable deadtime lead, referenced to V _{SS} (AUIRS21844 only)
V_{SS}	Logic ground (AUIRS21844 only)
V_{B}	High-side floating supply
НО	High-side gate drive output
V_S	High-side floating supply return
V_{CC}	Low-side and logic fixed supply
LO	Low-side gate drive output
COM	Low-side return

Lead Assignments: AUIRS2184(4)S





Application Information and Additional Details



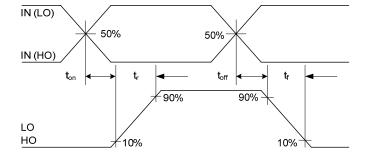


Figure 1: Input/Output Timing Diagram

Figure 2: Switching Time Waveform Definitions

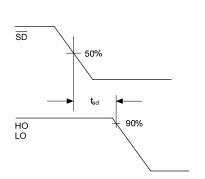


Figure 3: Shutdown Waveform Definitions

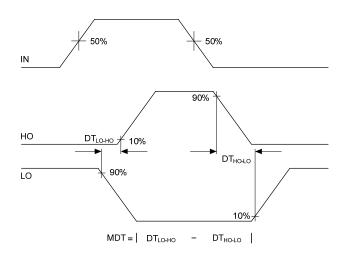


Figure 4: Deadtime Waveform Definitions

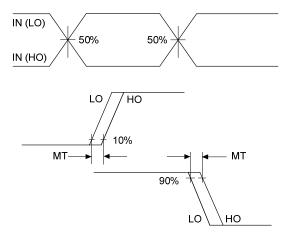


Figure 5: Delay Matching Waveform Definitions



Parameter Trends vs. Temperature and vs. Supply Voltage

Figures of this chapter provide information on the experimental performance of the AUIRS2184(4)S HVIC. The line plotted in each figure is generated from actual lab data.

A large number of individual samples were tested at three temperatures (-40 °C, 25 °C, and 125 °C) in order to generate the experimental curve. The line consists of three data points (one data point at each of the tested temperatures) that have been connected together to illustrate the understood trend. The individual data points on the Typ. curve were determined by calculating the averaged experimental value of the parameter (for a given temperature).

A different set of individual samples was used to generate curves of parameter trends vs. supply voltage.

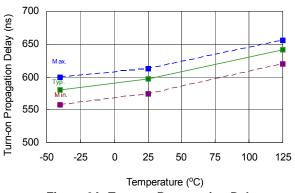


Figure 6A. Turn-on Propagation Delay vs. Temperature

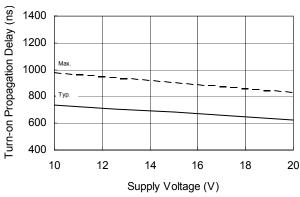


Figure 6B. Turn-on Propagation Delay vs. Supply Voltage

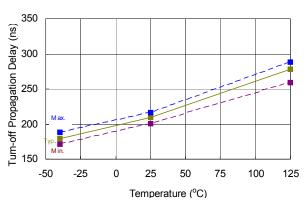


Figure 7A. Turn-off Propagation Delay vs. Temperature

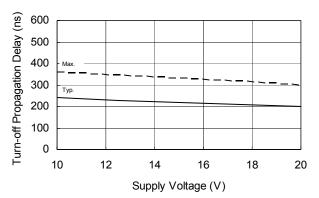


Figure 7B. Turn-off Propagation Delay vs. Supply Voltage

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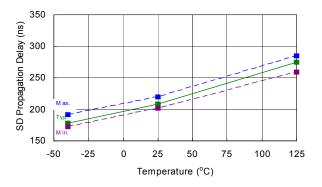


Figure 8A. SD Propagation Delay vs. Temperature

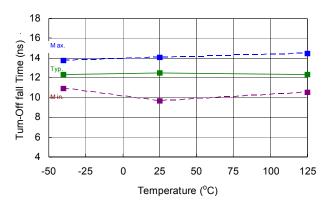


Figure 9A. Turn-off Fall Time vs. Temperature

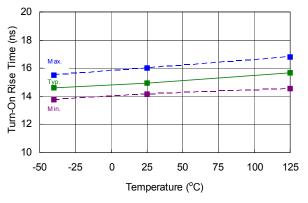


Figure 10. Turn-on Rise Time vs. Temperature

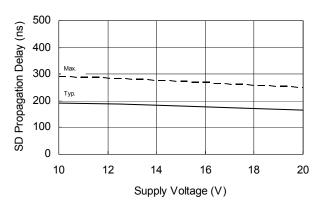


Figure 8B. SD Propagation Delay vs. Supply Voltage

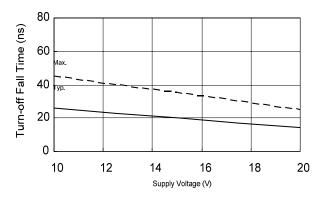


Figure 10B. Turn-off Fall Time vs. Supply Voltage

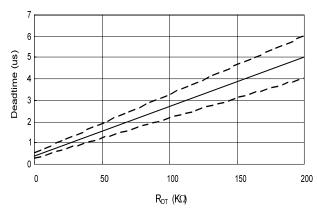


Figure 11. Deadtime vs R_{DT}

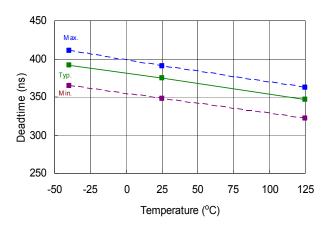


Figure 12A. Deadtime vs Temperature

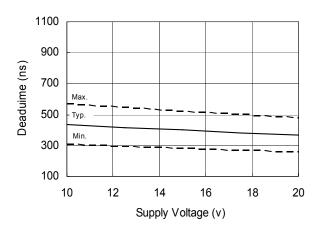


Figure 12B. Deadtime vs. Supply Voltage

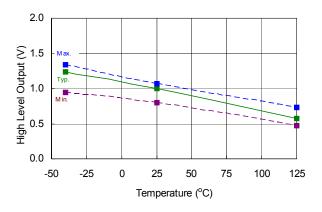


Figure 13. High Level Output vs. Temperature (I₀ = 0 mA)

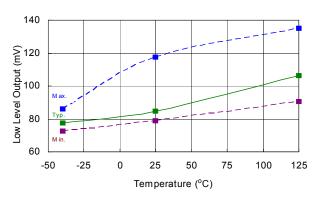


Figure 14. Low Level Output vs. Temperature

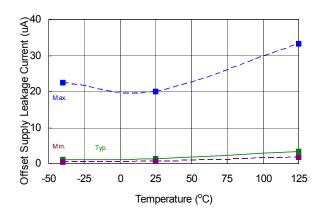


Figure 15. Offset Supply Leakage Current vs.
Temperature

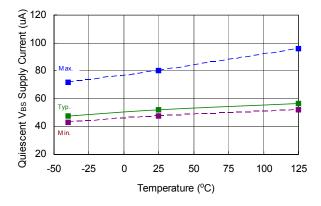


Figure 16. V_{BS} Supply Current vs. Temperature

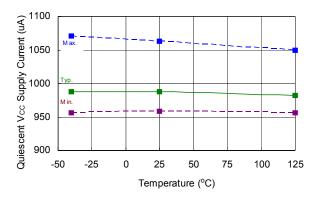


Figure 17A. V_{cc} Supply Current vs. Temperature

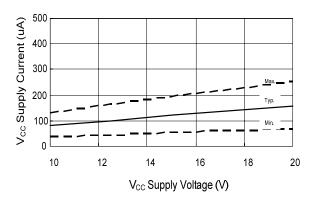


Figure 17B. V_{CC} Supply Current vs. V_{CC} Supply Voltage (V)

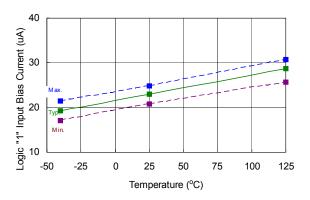


Figure 18. Logic "1" Input Bias Current vs. Temperature

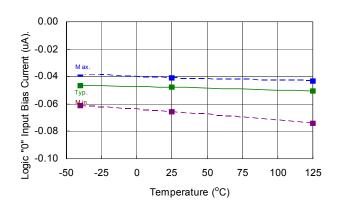


Figure 19. Logic "0" Input Bias Current vs. Temperature

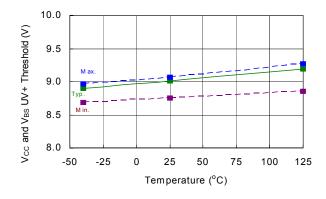


Figure 20. V_{CC} and V_{BS} Undervoltage Threshold (+) vs. Temperature

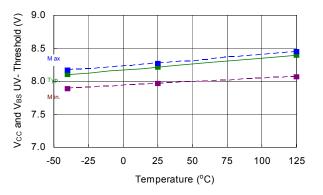


Figure 21. V_{CC} and V_{BS} Undervoltage Threshold (-) vs. Temperature



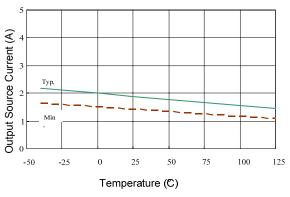


Figure 22. Output Source Current (A) vs. Temperature

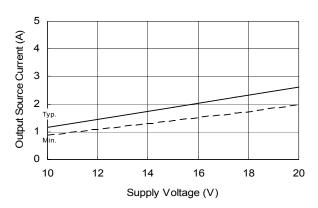


Figure 22A. Output Source Current (A) vs. Supply Voltage (V)

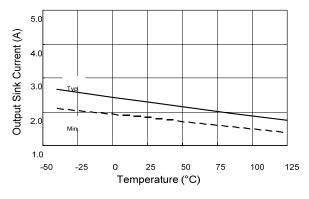


Figure 23. Output Sink Current (A) vs. Temperature

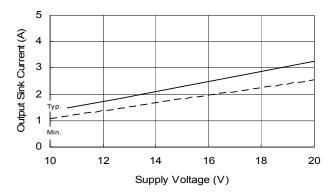
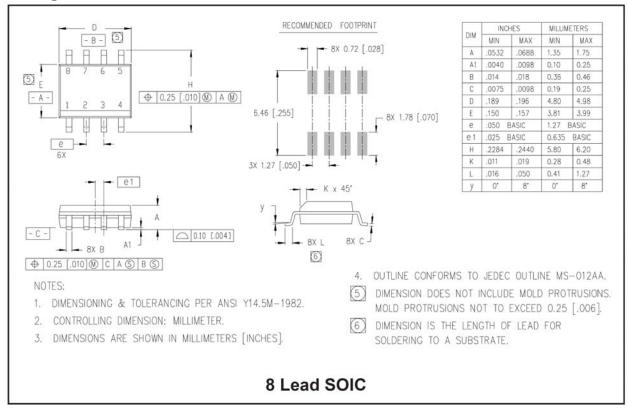
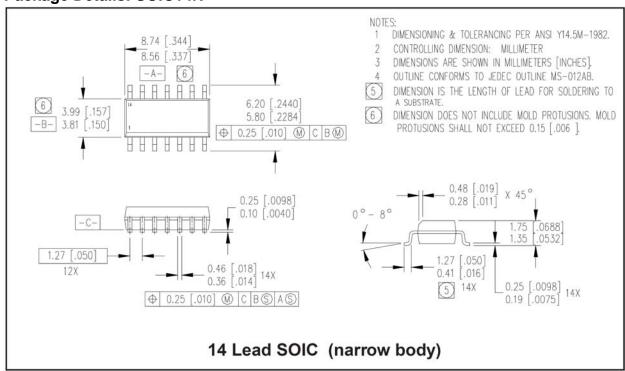


Figure 23A. Output Sink Current (A) vs. Supply Voltage (V)

Package Details: SOIC8

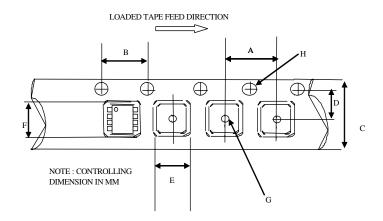


Package Details: SOIC14N



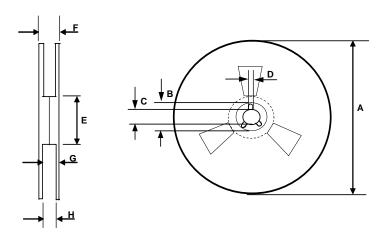


Tape and Reel Details: SOIC8



CARRIER TAPE DIMENSION FOR 8SOICN

	Me	etric	Imp	erial
Code	Min	Max	Min	Max
A B	7.90	8.10	0.311	0.318
	3.90	4.10	0.153	0.161
С	11.70	12.30	0.46	0.484
D	5.45	5.55	0.214	0.218
E F	6.30	6.50	0.248	0.255
	5.10	5.30	0.200	0.208
G	1.50	n/a	0.059	n/a
Н	1.50	1.60	0.059	0.062

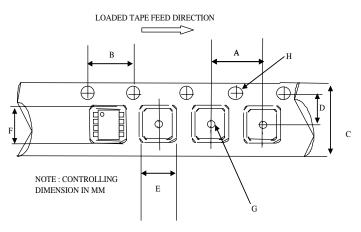


REEL DIMENSIONS FOR 8SOICN

	Metric Impe			erial	
Code	Min	Max	Min	Max	
Α	329.60	330.25	12.976	13.001	
В	20.95	21.45	0.824	0.844	
С	12.80	13.20	0.503	0.519	
D	1.95	2.45	0.767	0.096	
E	98.00	102.00	3.858	4.015	
F	n/a	18.40	n/a	0.724	
G	14.50	17.10	0.570	0.673	
Н	12.40	14.40	0.488	0.566	

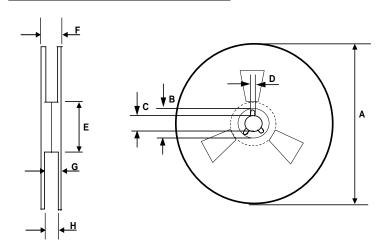


Tape and Reel Details: SOIC14N



CARRIER TAPE DIMENSION FOR 14SOICN

	Me	etric	Imp	erial			
Code	Min	Max	Min	Max			
Α	7.90	8.10	0.311	0.318			
В	3.90	4.10	0.153	0.161			
C	15.70	16.30	0.618	0.641			
D	7.40	7.60	0.291	0.299			
E F	6.40	6.60	0.252	0.260			
F	9.40	9.60	0.370	0.378			
G	1.50	n/a	0.059	n/a			
Н	1.50	1.60	0.059	0.062			



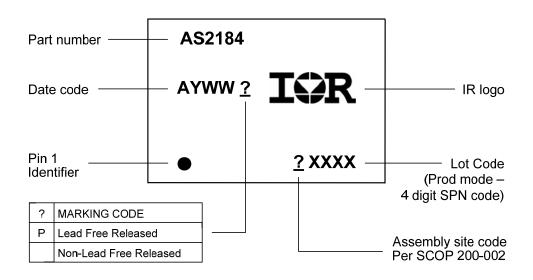
REEL DIMENSIONS FOR 14SOICN

	Metric		Imperial		
Code	Min	Max	Min	Max	
Α	329.60	330.25	12.976	13.001	
B C	20.95	21.45	0.824	0.844	
С	12.80	13.20	0.503	0.519	
D	1.95	2.45	0.767	0.096	
E	98.00	102.00	3.858	4.015	
F	n/a	22.40	n/a	0.881	
G	18.50	21.10	0.728	0.830	
Н	16.40	18.40	0.645	0.724	

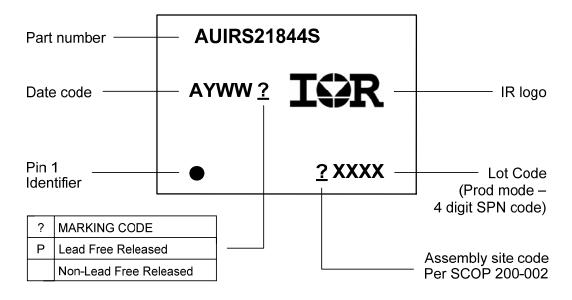


Part Marking Information

SOIC8:



SOIC14N:





Ordering Information

Base Part Number	Package Type	Standard Pack		Occupate Boot Name Lon
		Form	Quantity	Complete Part Number
AUIRS2184S	SOIC8	Tube/Bulk	55	AUIRS2184S
		Tape and Reel	2500	AUIRS2184STR
AUIRS21844S	SOIC14N	Tube/Bulk	55	AUIRS21844S
		Tape and Reel	2500	AUIRS21844STR



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Revision History

Date	Comment				
04/29/08	Draft				
5/6/08	Converted to automotive format				
5/13/08	Corrected various formatting issues and typos (e.g. /SD) Corrected typical application dwg				
5/16/08	Inserted figures 1-5				
5/22/08	Added graphs for parameter temperature trends				
5/26/08	Added missing graphs, added note on PbF and auto qualification on features list				
5/28/08	Added date				
9/30/08	Reviewed and updated various missing information				
10/01/08	Inserted Input/Output Pin Equivalent Circuit Diagram				
Feb13 th , 2009	Typ application changes				
6/04/09	Updated package information, qualification information, and tri-temp waveforms				
8/4/09	Updated qualification information; graphs 27-42 changed 2181(4) to 2184(4)				
8/6/09	Removed characterization graphs 27-42.				
8/11/09	Updated package type and marking info				
9/15/09	Corrected chapter with Parameter Trends SD max propagation delay changed from 270ns to 300ns Turn on rise time typ value changed from 40nsec to 20nsec				
9/19/09	Rearranged temperature characteristic graphs and added actual part number on marking drawings				
9/21/09	Added ESD passing voltages, updated table of contents.				
9/22/09	Typ application section updated				
9/23/09	Added note 1 for Vcc under Abs Max rating				
12/17/09	Front page: changed ton/toff typ. to 600ns/230ns, Page6: changed Ton typ.=600ns; toff typ.=230ns; tsd typ.=220ns, max=350ns; MTon typ.=3ns; MToff typ.=15ns; tr typ=15ns; tf typ=12ns, DT ($R_{\rm DT}$ @200Kohms) min=3.9uS; DT (0-ohm) typ=375ns; VOH max.=1.5V; iqbs min.=10uA, typ=50uA, max=130uA; Iqcc max.=1.3mA; added Important Notice page				
12/22/09	Corrected MSL level on qual info page to MSL3 and updated MM ESD passing voltage to +/-100V instead of +/-150V.				
02/24/2010	Updated disclaimer under Abs. Max. Rating Page 6: Added I _{O25+} and I _{O25-} specification and the note				
Jul. 27, 2010	clamp diode values changed from 25V into 20V (in-out pin eq. circ. diagrams)				

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